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10667227

SEMICONDUCTOR PACKAGE AND

METHOD OF MAKING

Title of Invention:

LEADFRAME HAVING LEAD

LOCKS TO SECURE LEADS TO

ENCAPSULANT

First Named Inventor:

Jae Yee

Domestic/Foreign Application:

Domestic Application

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Electronic Version v1.1
Stylesheet Version v1.1.0

Title of Invention

SEMICONDUCTOR PACKAGE AND METHOD OF MAKING LEADFRAME HAVING LEAD LOCKS TO SECURE LEADS TO ENCAPSULANT

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Jae Hak Yee

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Submitted by:	Elec. Sign.	Sign. Capacity
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney

Documents being submitted

Files

us-ids

ids6-usidst.xml

us-ids.dtd

us-ids.xsl

Comments

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18 Stylesheet Version v18.0

> Title of Invention

SEMICONDUCTOR PACKAGE AND METHOD OF MAKING LEADFRAME HAVING LEAD LOCKS TO SECURE LEADS TO ENCAPSULANT

Application Number:

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Confirmation Number: 7012

First Named Applicant: Jae Yee

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(6388336 or 6395578 or 6400004 or 6410979 or 6414385 or 6420779 or 6429508 or 6437429 or 6444499 or 6448633 or 6452279 or 6464121 or 6476474 or 6476469 or 6482680 or 6498392 or 6498099 or 6507120 or 6507096 or 6534849

or 6545345 or 6559525 or 6566168).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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	2	6395578	2002-05-28	SHIN ET AL.			
	3	6400004	2002-06-04	FAN ET AL.			
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	11	6452279	2002-09-17	SHIMODA			
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22	6559525	2003-05-06	HUANG
23	6566168	2003-05-20	GANG

Signature

Examiner Name	Date